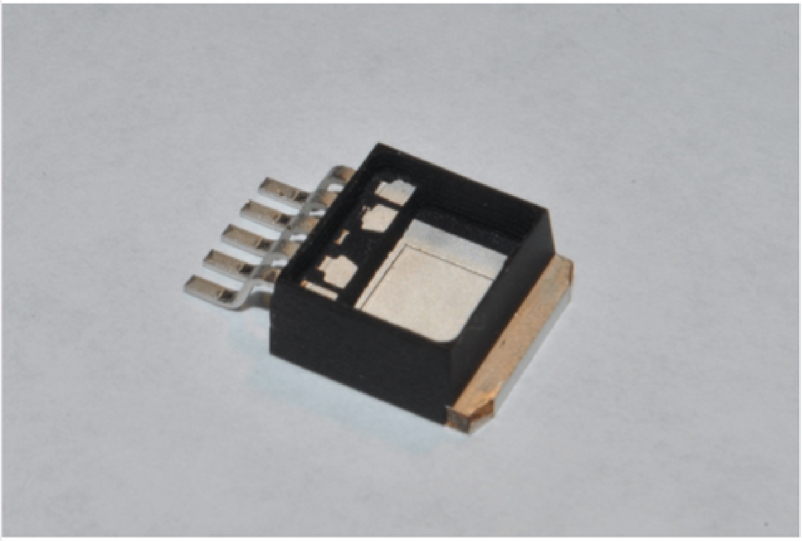
This Month at QP Technologies

We're into the dog days of summer in the Northern Hemisphere, and the tradeshow season is going strong. This week is the IMAPS Advanced System-in-Package (SiP) Conference, which runs online through Thursday, August 12. QP Technologies is a Presenting Partner this year, so if you plan to attend, please drop by our virtual booth and check out our offerings. If you're not yet registered, you can sign up via the above link. Next month, we'll be live and in person at Sensors Converge in San Jose, Calif. – more on that in our next issue!



Tech Feature of the Month: OCPP

Fast-turn prototype package assembly is often employed for rapid IC design verification. Our open-cavity plastic packages (OCPP) are an attractive quick-turn assembly option when COTS prototype packages are not available. QP Technologies can convert any existing IC plastic packages, whether dummies, electrical test rejects or excess inventory, into open-cavity packages, ready to be assembled with new die. OCPP is also a great interim solution for optimizing your package and working out any kinks before transitioning it to our Open-molded Plastic Package (OmPP™) family of air-cavity QFNs.

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Employee Spotlight

QP Technologies continues to grow and expand our capabilities, while maintaining the high level of quality our customers expect. To this end, we've brought on board a seasoned executive with more than three decades of industry experience. Darin Valley, our new director of quality assurance, joined QP Technologies from Cohu's Delta Design Philippines subsidiary. A Lean Six Sigma practitioner, Darin oversees our quality engineering, assurance and control activities, and is responsible for maintaining and elevating all quality-related programs, particularly ISO 9001, ISO 13485 and ITAR. Welcome, Darin, to the QP Tech family!

Virtual Tour

Early last year, QP Technologies relocated our headquarters to our wholly owned, 20,000-square-foot facility in Escondido, Calif. Built out specifically to accommodate our production processes, the building's layout is set up to follow the flow of material as it moves through the line. This allows us to streamline our processes and achieve improved manufacturing efficiencies. To take a virtual tour, click on the video below:

WATCH NOW

About QP Technologies

QP Technologies is a leading provider of microelectronic packaging and assembly, wafer preparation, and substrate design and development services. We leverage proven technologies developed by our skilled staff, and we work closely with you to get your products to market quickly, with the highest quality prototype and production volumes.

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